

CLAIM AMENDMENTS

IN THE CLAIMS

This listing of the claims will replace all prior versions, and listing, of claims in the application or previous response to office action:

Claims 1-5 (canceled).

Claim 6 (**Currently Amended**): A method for the production of circuit boards comprising the following steps in the sequential order of:

drilling through-bores for establishing through-connections;

through-connecting, wherein an electrically conductive general layer is built up;

etching a strip conductor image into the electrically conductive general layer;

filling of the bores of the through-connections with a medium;

lacquering of the surfaces on which through-connections are present and, at least in the proximity of which, strip conductors are later provided;

applying an insulating lacquer to the surfaces of the circuit board; and

producing strip conductors arranged above the through-connections,

wherein between the steps of etching and applying an insulating lacquer no further layers are applied to said circuit boards.

Claim 7 (previously presented): The method as claimed in claim 6, wherein the medium used in filling the bores and insulating lacquer is identical.

Claim 8 (**Currently Amended**): The method as claimed in claim 6, wherein the medium used in filling the bores and the insulating lacquer is a standard media variant non-resistant to etching.

Claim 9 (previously presented): The method as claimed in claim 6 wherein the strip conductors arranged above the through-connections are carbon.

Claim 10 (previously presented): The method as claimed in claim 6, further comprising separating individual circuit boards by means of a milling process.

Claim 11 (previously presented): The method as claimed in claim 6, wherein the through-bores are 20 μm in size.

Claim 12 (previously presented): The method as claimed in claim 6, wherein the insulating lacquer is an International Standard Organization lacquer.

Claim 13 (**NEW**): A method for the production of circuit boards comprising the following steps in the sequential order of:

- drilling through-bores for establishing through-connections;
- through-connecting, wherein an electrically conductive general layer is built up;
- etching a strip conductor image into the electrically conductive general layer;
- filling of the bores of the through-connections with a medium;
- without brushing said circuit board, lacquering of the surfaces on which through-connections are present and, at least in the proximity of which, strip conductors are later provided;
- applying an insulating lacquer to the surfaces of the circuit board; and
- producing strip conductors arranged above the through-connections.

Claim 14 (**NEW**): The method as claimed in claim 13, wherein the medium used in filling the bores and insulating lacquer is identical.

Claim 15 (**NEW**): The method as claimed in claim 13, wherein the medium used in filling the bores and the insulating lacquer is non-resistant to etching.

Claim 16 (**NEW**): The method as claimed in claim 13, wherein the strip conductors arranged above the through-connections are carbon.

Claim 17 (**NEW**): The method as claimed in claim 13, further comprising separating individual circuit boards by means of a milling process.

Claim 18 (**NEW**): The method as claimed in claim 13, wherein the through-bores are 20 μm in size.

Claim 19 (**NEW**): The method as claimed in claim 13, wherein the insulating lacquer is an International Standard Organization lacquer.

Claim 20 (**NEW**): A method for the production of circuit boards comprising the following steps in the sequential order of:

- drilling through-bores for establishing through-connections;
- through-connecting, wherein an electrically conductive general layer is built up;
- etching a strip conductor image into the electrically conductive general layer;
- filling of the bores of the through-connections with a medium;
- without brushing said circuit board, lacquering of the surfaces on which through-connections are present and, at least in the proximity of which, strip conductors are later provided;
- applying an insulating lacquer to the surfaces of the circuit board; and
- producing strip conductors arranged above the through-connections,

wherein between the steps of etching and applying an insulating lacquer no further layers are applied to said circuit boards.

Claim 21 (**NEW**): The method as claimed in claim 20, wherein the medium used in filling the bores and insulating lacquer is identical.

Claim 22 (**NEW**): The method as claimed in claim 20, wherein the medium used in filling the bores and the insulating lacquer is non-resistant to etching.

Claim 23 (**NEW**): The method as claimed in claim 20, wherein the strip conductors arranged above the through-connections are carbon.

Claim 24 (**NEW**): The method as claimed in claim 20, further comprising separating individual circuit boards by means of a milling process.

Claim 25 (**NEW**): The method as claimed in claim 20, wherein the through-bores are 20 μm in size.